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Attorney Docket Number

U.S. PATENT DOCUMENTS						
Examiner Initials*	Cite No.1	Document Number Number-Kind Code ² (If known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	
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FOREIGN PATENT DOCUMENTS								
Examiner		Τ,	Cite	Foreign Patent Document	Publication	Name of Patentee or	Pages, Columns, Lines,	
	Initials*		10.1	Country Code ³ -Number ⁴ -Kind Code ⁵ (If known)	Date MM-DD-YYYY	Applicant of Cited Document	Where Relevant Passages or Relevant Figures Appear	ן™
N	ゕ	\downarrow		DE3233195	03-17-1983	Mitsubishi Electric Corp.		П
				JP2037655	02-07-1990	Siemens AG		П
Γ	Π		,	JP3127816	05-30-1991	Canon KK		П
	レ	1		JP3174715	07-29-1991	Fujitsu Limited		
M				WO 98/19337	05-07-1998	Trusi Technologies, LLC		

NON PATENT LITERATURE DOCUMENTS						
Examiner Initials	Cite No.1	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T²			
MC	1	Wolf, Stanley and Richard N. Tauber; Silicon Processing For the VLSI Era, Volume 1: Process Technology; Sunset Beach, CA: Lattice Press, 1986, pages 191-194				
		European Search Report for Application No. EP 02 00 9643 (date completed: October 8, 2002)				
j		Phys. Rev. B., Condens. Matter Matter. Phys. (USA), Physical Review B (Condensed Matter and Materials Physics), 15 March 2003, APS through AIP, USA.				
MC		S. Wolf, Silicon Processing For the VLSI Era, 1990, Lattice Press, Volume 2, page 191.				
ML	<u> </u>	Svechnikov, S.V.; Kobylyatskaya, M.F.; Kimarskii, V.I.; Kaufman, A.P.; Kuzolev, Yu. I.; Cherepov, Ye. I.; Fomin, B.I.; "Switching Card With Aluminum Membrane Current Lead Crossovers";1972				
M		Salazar, M.; Wilkins, C.W., Jr.; Ryan, V.W.; Wang, T.T.; "Low stress films of cyclized polybutadiene dielectrics by vacuum annealing"; Oct. 21-22, 1986; pp. 96-102.				
<u> </u>		Allen, Mark G.: Senturia, Stephen D.; "Measurement of polymide interlayer adhesion using microfabricated structures"; 1988; pp. 352-356.				
MC		Kochugova, I.V.; Nikolaeva, L.V.; Vakser, N.M., (M.I. Kalinin Leningrad Polytechnic Institute (USSR); "Electrophysical investigation of thin-layered inorganic coatings"; 1989; pp. 826-828.				

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